

ABSTRACT

The present invention relates to a technique for determining a dressing condition for dressing a polishing pad used for polishing a workpiece, such as a wafer, a substrate, or a panel. A dressing-condition determining apparatus (60) includes a memory (60a) storing an estimation model (62) constructed by machine learning, and a processor (60b) configured to execute an arithmetic operation according to an algorithm of the estimation model (62). The estimation model (62) is configured to output the dressing condition for realizing target paths of a plurality of abrasive grains on the polishing pad (2) when a target-path image indicating the target paths is inputted into the estimation model (62). The plurality of abrasive grains constitute the dressing surface (51a).

FIG. 1